TriQuint SEMICONDUCTOR

TGA4943-SL

28 Gb/s 8Vpp Optical Modulator Driver

TGA4943
0850 267
D1082225

Measured Performance

Bias conditions: Vd1,2,3 = 7 V, Idq = 310 mA,
Vc1,2,3 = 0.7, 0.7, 0.8 V Typical

22 Gb/s, 0.48 Vpp Input, Vout = 8 Vpp.

DQPSK

mean	1.890970 mW	median 1.895587 mW
std dev	124.193 µW	hits 14.53 khits
p-p	1.03460 mW	µ±1σ 70.7 %
peak	964 hits	µ±2σ 96.2 %
pk pos	1.93254 mW	µ±3σ 99.8 % source: 1
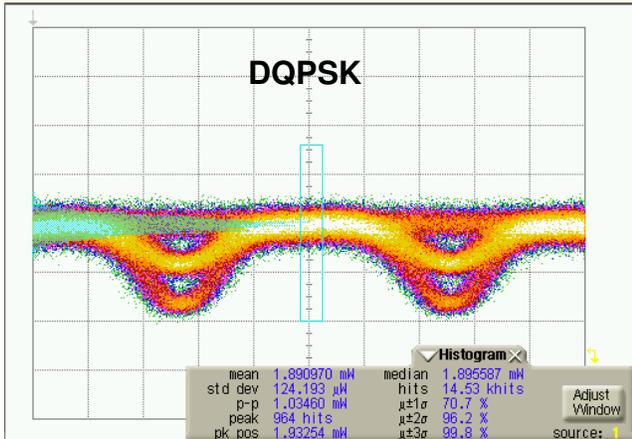
Vin = 0.5 Vpp, Vout = 8Vpp, 21.5 Gbps, PRBS 2^31 -1
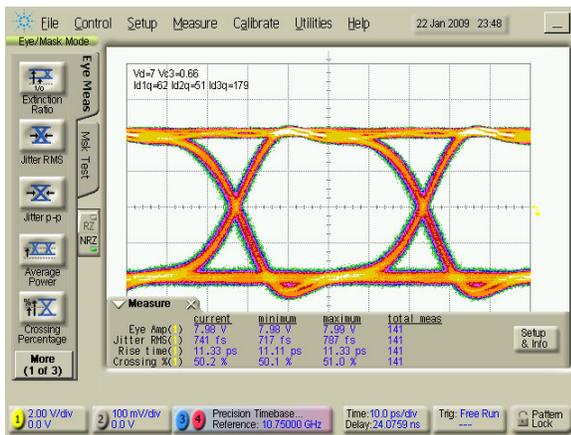
Key Features

- 28 Gb/s Performance
- Single Ended Input and Output
- Adjustable Output Amplitude, 3 Vpp – 9 Vpp
- Low Additive RMS Jitter, 400 fsec
- High Output Drive, 8Vpp with 0.4 Vpp Input
- Gain, 32 dB at 20 GHz
- Low DC Power Dissipation, 1.7 W for Vout = 8Vpp at Vd=6 V
- Rise Times <12 psec
- Hot Pluggable
- Package Size: 14.4 x 7 x 2 mm

Primary Applications

- 40 GB/s Optical Market: DQPSK   (2x)
- 100 GB/s Optical Market: DP-QPSK   (4x)

Product Description

The TriQuint TGA4943-SL is a three stage optical modulator driver amplifier designed to operate at frequencies that target the 28 Gb/s optical market using an 14.4 x 7 x 2 mm surface mount system in package (SIP).

The TGA4943-SL consists of three high performance wideband amplifiers assembled in a surface mount package combined with a minimum of off-chip components. A single TGA4943-SL placed between the MUX and Optical Modulator provides OEMs with a modulator driver surface mount solution.

The TGA4943-SL provides Metro and Long Haul designers with system critical features such as: low power dissipation, low rail ripple, high voltage drive capability (3 Vpp amplitude adjustable up to 9 Vpp), low output jitter, and low input drive sensitivity (0.4 Vpp – 1 Vpp at Vout = 8Vpp).

The TGA4943-SL is lead-free and RoHS compliant. Evaluation boards are available upon request.

Datasheet subject to change without notice.

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TGA4943-SL

Table I
Absolute Maximum Ratings   1/

Symbol	Parameter	Value	Notes
Vd1, Vd2, Vd3	Drain Voltage	9 V	2/ 3/ 4/
Vd1-Vg1, Vd2-Vg2, Vd3-Vg3	Drain to Gate Voltage	10 V	2/ 3/ 4/
Vg1, Vg2, Vg3	Gate Voltage Range	-5 to 0 V	
Vc1, Vc2, Vc3	Control Voltage Range	(Vd-7) to +6 V	3/ 4/
Id1, Id2	Drain Current	100 mA	2/
Id3	Drain Current	250 mA	2/
Ig1, Ig2, Ig3	Gate Current Range	-15 to 21 mA	4/
Ic1, Ic2, Ic3	Control Current Range	-15 to 21 mA	4/
Vin_pp	Peak-Peak Input Voltage	7 V	
Pin	Input Continuous Wave Power	24 dBm	2/
Pd	Max Power Dissipation	3.05	5/
Tch	Maximum Channel Temperature	200 °C	

1/   These ratings represent the maximum operable values for this device. Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device and / or affect device lifetime. These are stress ratings only, and functional operation of the device at these conditions is not implied.

2/   Combinations of supply voltage, supply current, input power, and output power shall not exceed the maximum power dissipation listed in Table IV.

3/   Assure $-0.5 \leq Vd - Vc \leq 7$ V.

4/   HOT PLUGGABLE: Comply with voltage and currents outlined in Max Ratings Table.

5/   Maximum Power Dissipation is based upon Baseplate temperature of 80 °C and Channel Temperature of 200 °C, using the thermal resistance published in Table IV.

**Table II
Recommended Operating Conditions**

Output Voltage (Vpp)	Drain Voltage: Vd1, Vd2, Vd3 (V)	Quiescent Drain Current: Idq1, Idq2, Idq3 (mA)	Under RF Drive Drain Current: Id1+ Id2 + Id3 (mA)	Control Voltage: Vc1, Vc2, Vc3 (V)	Gate Voltage: Vg1, Vg2, Vg3 (V)*	Pdiss (W)
3.6	5	40, 30, 84	198	0.7, 0.7, -0.23	-0.56, -1.89, -1.34	0.96
4	5	40, 30, 100	207	0.7, 0.7, -0.01	-0.56, -1.89, -1.25	1.00
5	5	40, 30, 133	230	0.7, 0.7, 0.23	-0.56, -1.89, -1.09	1.09
6	5	40, 30, 160	254	0.7, 0.7, 0.42	-0.56, -1.89, -0.97	1.18
7.8	5	40, 30, 191	296	0.7, 0.7, 0.70	-0.56, -1.89, -0.85	1.33
4	6	51, 51, 63	233	0.7, 0.7, -0.06	-0.51, -1.68, -1.53	1.32
5	6	51, 51, 100	257	0.7, 0.7, 0.14	-0.51, -1.68, -1.30	1.42
6	6	51, 51, 135	281	0.7, 0.7, 0.36	-0.51, -1.68, -1.11	1.51
7	6	51, 51, 167	305	0.7, 0.7, 0.59	-0.51, -1.68, -0.95	1.59
8	6	51, 51, 201	330	0.7, 0.7, 0.86	-0.51, -1.68, -0.78	1.66
6	7	62, 50, 98	302	0.7, 0.7, 0.24	-0.47, -1.74, -1.34	2.03
7	7	62, 50, 144	326	0.7, 0.7, 0.45	-0.47, -1.74, -1.09	2.16
8	7	62, 50, 179	348	0.7, 0.7, 0.66	-0.47, -1.74, -0.92	2.28
9	7	62, 50, 223	373	0.7, 0.7, 0.91	-0.47, -1.74, -0.69	2.4
10	8	82, 73, 240	434	0.7, 0.7, 2.04	-0.4, -1.52, -0.61	2.97

* Gate and control voltages should be adjusted to reach target drain currents and optimal eye performance and may vary from above voltages.

Table III
RF Characterization Table

Bias: Vd = 7 V, Idq=300 mA, Vc1, Vc2 = 0.7 V, Vc3 = +0.8 V, typical

Small Signal Characteristics

SYMBOL	PARAMETER	TEST CONDITIONS	MIN	NOMINAL	MAX	UNITS
Gain	Small Signal Gain	f = 0.1 - 20 GHz	-	32	-	dB
		f = 20.1 - 30 GHz	-	30	-	
		f = 30.1 - 36 GHz	-	28	-	
		f = 36.1 – 40 GHz	-	20	-	
IRL	Input Return Loss	f = 0.1 - 10 GHz	-	15	-	dB
		f = 10.1 - 20 GHz	-	13	-	
		f = 20.1 – 30 GHz		11		
		f = 30.1 – 40 GHz		4		
ORL	Output Return Loss	f = 0.1 - 24 GHz	-	15	-	dB
		f = 24.1 - 34 GHz	-	8	-	
		f = 34.1 – 40 GHz		6		
BW	3 dB Bandwidth	f(x) – f(1 GHz) = 3 dB x = freq of 3 dB BW	-	27	-	GHz

Table III - Cont.
RF Characterization Table

Bias: Vd = 7 V, Idq = 300 mA, Vc1, Vc2 = 0.6 V, Vc3 = 0.8 V, typical

Electrical Eye Test Conditions: Vin = 0.5 Vpp, PRBS 2^{31}-1, 21.5 Gbps, Crossing = 50% +/- 2%

SYMBOL	PARAMETER	TEST CONDITIONS	MIN	NOMINAL	MAX	UNITS
Vout_Max	Maximum Eye Amplitude	500 mVpp Input	-	10	-	Vpp
Tr	Risetime	8 Vpp Output	-	11	-	psec
Tf	Falltime	8 Vpp Output		11		psec
SNR	Signal to Noise Ratio	8 Vpp Output		20		dB
Eye Opening	1/	8 Vpp Output		85		%
Jrms_Add	Additive Jitter 2/	8 Vpp Output		400		fsec
Jpp	P-P Jitter	8 Vpp Output		7		psec
Id	Total Drain Current	8 Vpp Output	-	375	-	mA

1/ Eye Opening defined as: [Eye Height (Vpp)/Eye Amplitude (Vpp)] *100

2/ Additive Jitter defined as: Sqrt [(Total RMS Jitter)^2 – (Input RMS Jitter)^2]

Table IV
Power Dissipation and Thermal Properties

Parameter	Test Conditions	Value	Notes
Thermal Resistance, θjc	Vd = 7 V Idq_tot = 300 mA Idq3=190 mA Pd_stage3 = 1.33 W Tbaseplate = 85 ℃	θjc = 39.4 ℃/W Tchannel = 137.4 ℃ Tm = 4.3 E+6 Hrs	1/, 2/
Thermal Resistance, θjc Under RF Drive	Vout = 8 Vpp, Vd = 7V Id3 = 190 mA Pd_stage3 =1.17 W Tbaseplate = 85 ℃	θjc = 39.4 ℃/W Tchannel = 131 ℃ Tm = 9.2 E+6 Hrs	
Storage Temperature		-65 to 150 ℃	

1/   Channel operating temperature will directly affect the device median lifetime (Tm). For maximum life, it is recommended that channel temperatures be maintained at the lowest possible levels.

2/   θjc is modeled based upon hottest stage (stage 3) because there is negligible thermal coupling between stages. It is the thermal resistance of the part calculated from the junction to the bottom of the TGA4943-SL package.

To calculate the temperature rise, calculate the dissipated power in the third stage (Pdiss = Idq3*Vd3) and multiply by θjc. For example: Tbase = 85 ℃, Idq3 = 190 mA, Vd3 = 7V. Pdiss_stage3 = 1.33 W. θjc=39.4 ℃/W. Temperature rise = θjc*Pdiss = 52.4 C; Tchannel = Tbase + Temp rise = 137.4 ℃

## Median Lifetime (Tm) vs. Channel Temperature
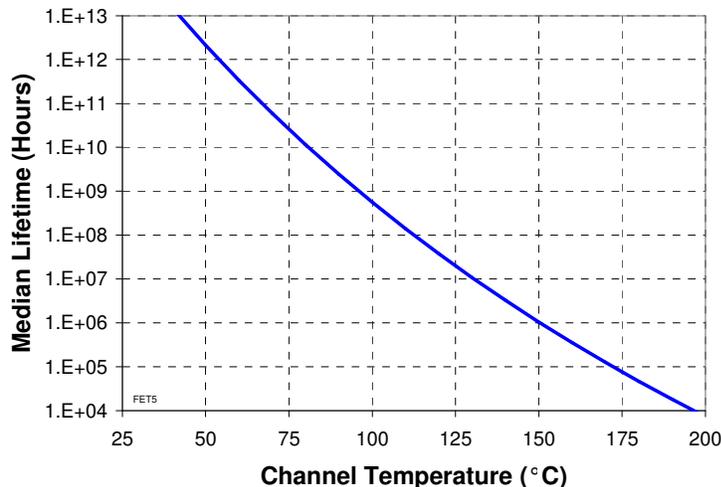
## Vd = 7 V, Vin = 0.5 Vpp, Vout = 6 Vpp, 21.5 Gb/s, PRBS 2^{31} -1
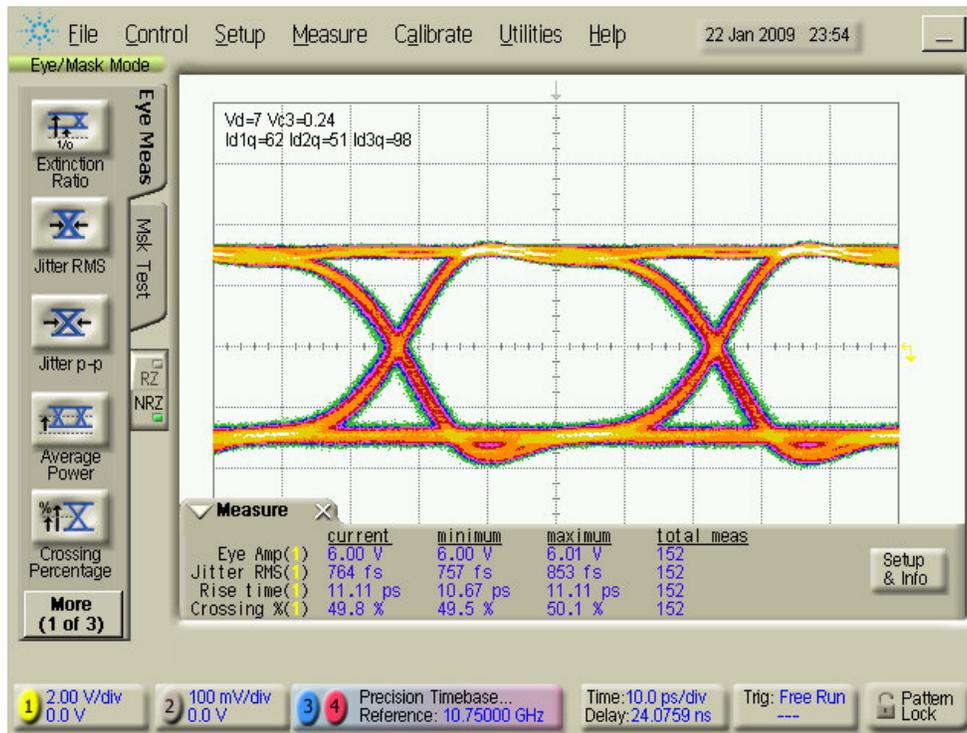
## Vd = 7 V, Vin = 0.5 Vpp, Vout = 7 Vpp, 21.5 Gb/s, PRBS 2^{31} -1
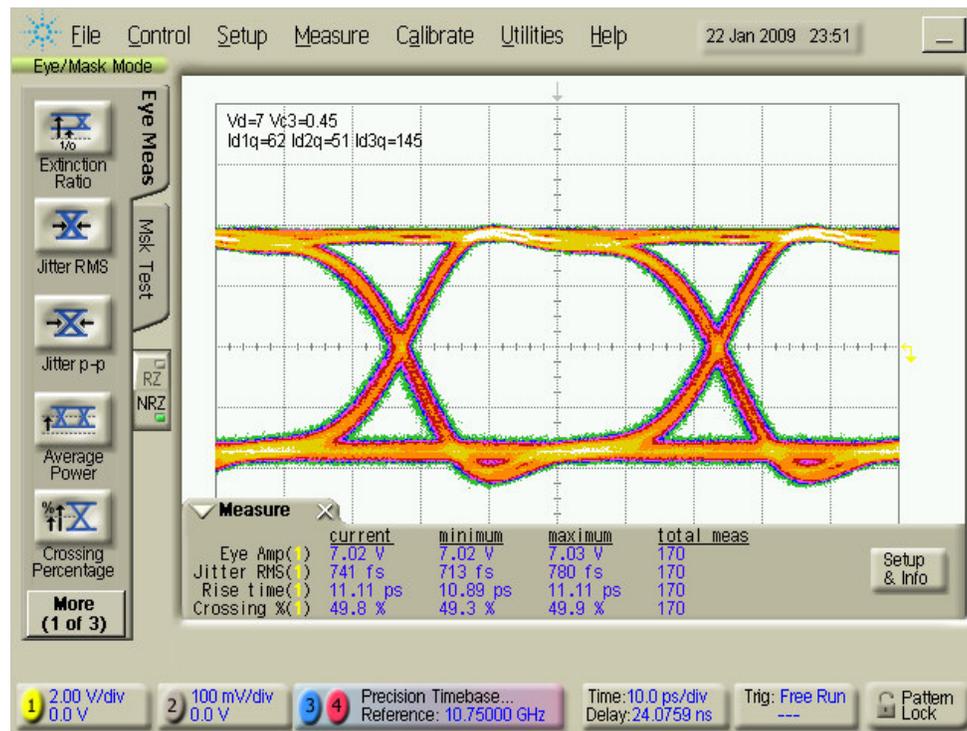
## Vd = 7 V, Vin = 0.5 Vpp, Vout = 8 Vpp, 21.5 Gb/s, PRBS 2^{31} -1
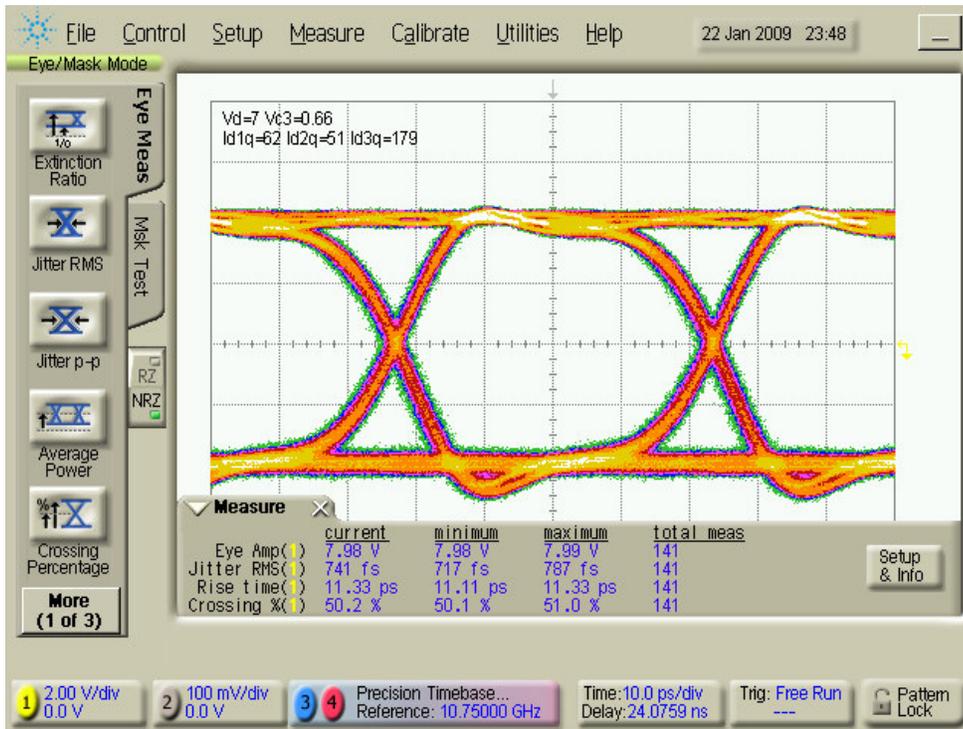
Vd = 7 V, Vin = 0.5 Vpp, Vout = 9 Vpp, 21.5 Gb/s, PRBS 2^{31} -1
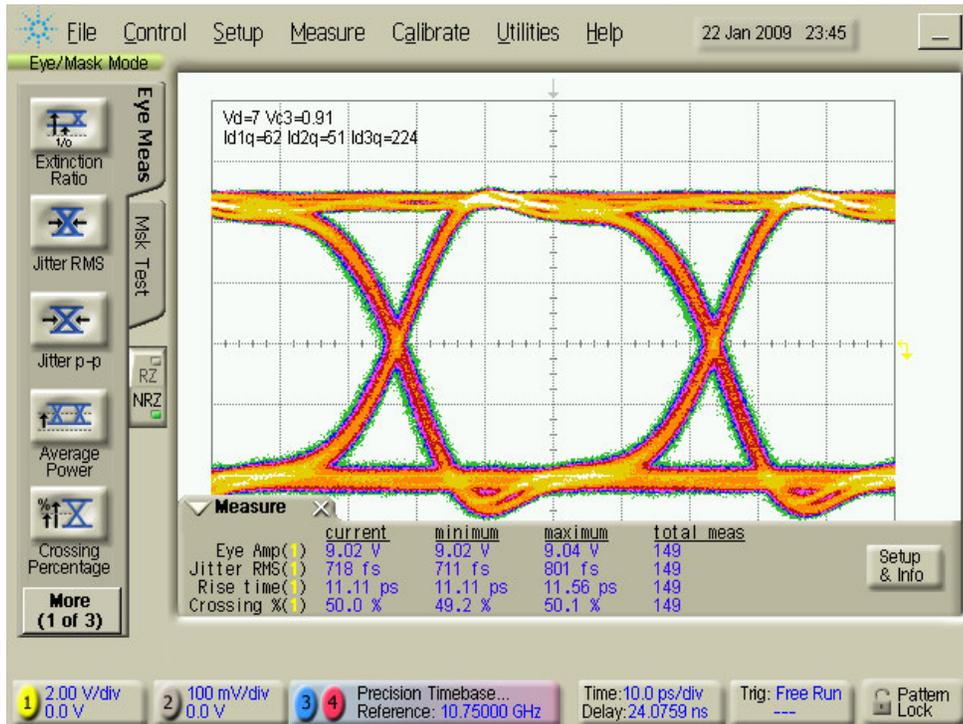
**Vd = 7 V, Vin = 0.5 Vpp, Vout = 10.6 Vpp, 28 Gb/s, PRBS 2^{31} -1**
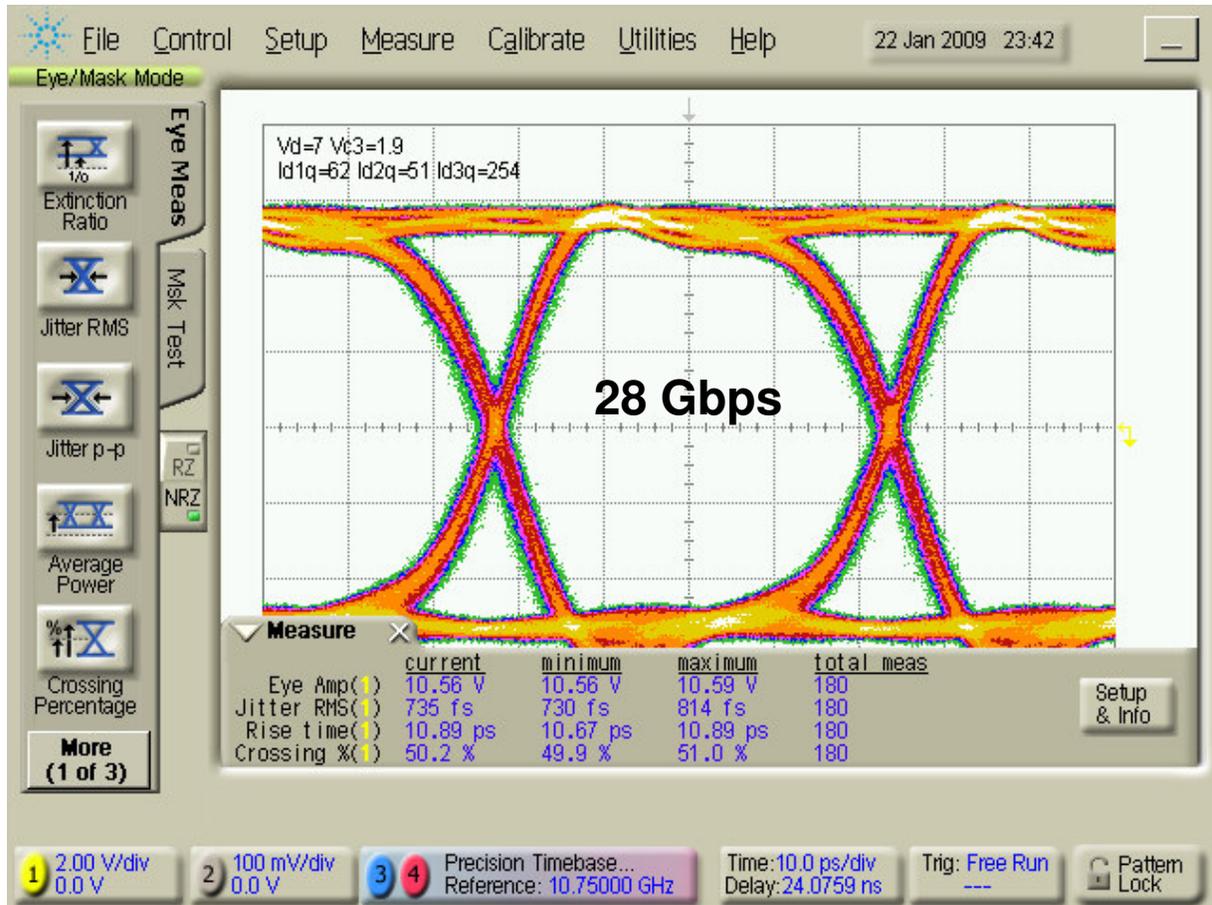
Measured Data: Vd = 7 V, Vc1, 2, 3 = 0.7, 0.7, 0.8 V, Idq1, 2, 3 = 40, 60, 210 mA, Vin = 0.48 Vpp, Vout = 8 Vpp, 22 Gb/s

DPSK

mean	1.604133 mW	median	1.599987 mW
std dev	92.1753 µW	hits	17.20 khits
p-p	812.90 µW	µ±1σ	73.5 %
peak	1.510 khits	µ±2σ	96.5 %
pk pos	1.61846 mW	µ±3σ	99.8 %

DQPSK

mean	1.890970 mW	median	1.895587 mW
std dev	124.193 µW	hits	14.53 khits
p-p	1.03460 mW	µ±1σ	70.7 %
peak	964 hits	µ±2σ	96.2 %
pk pos	1.93254 mW	µ±3σ	99.8 %

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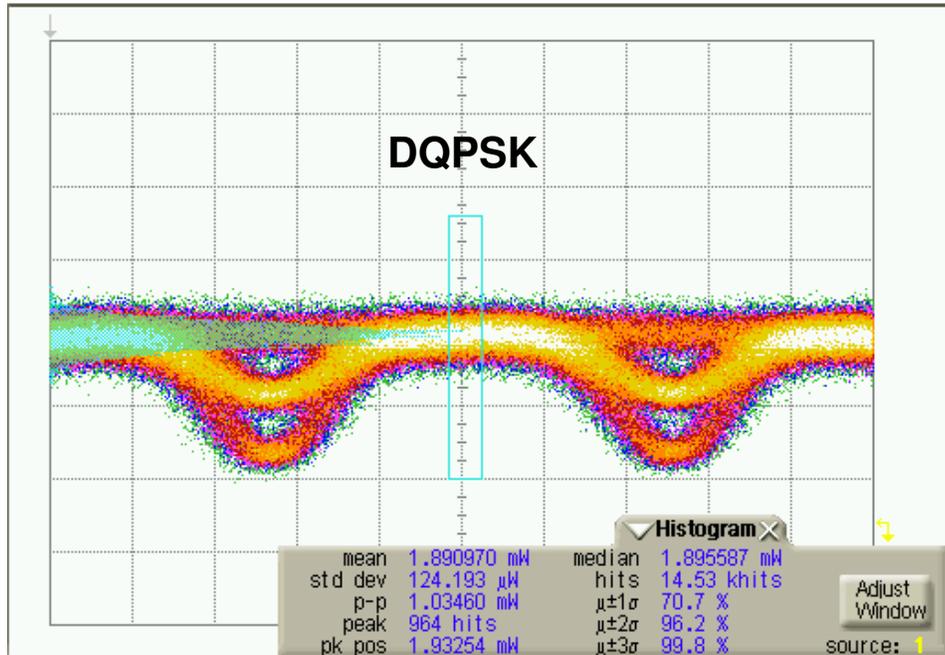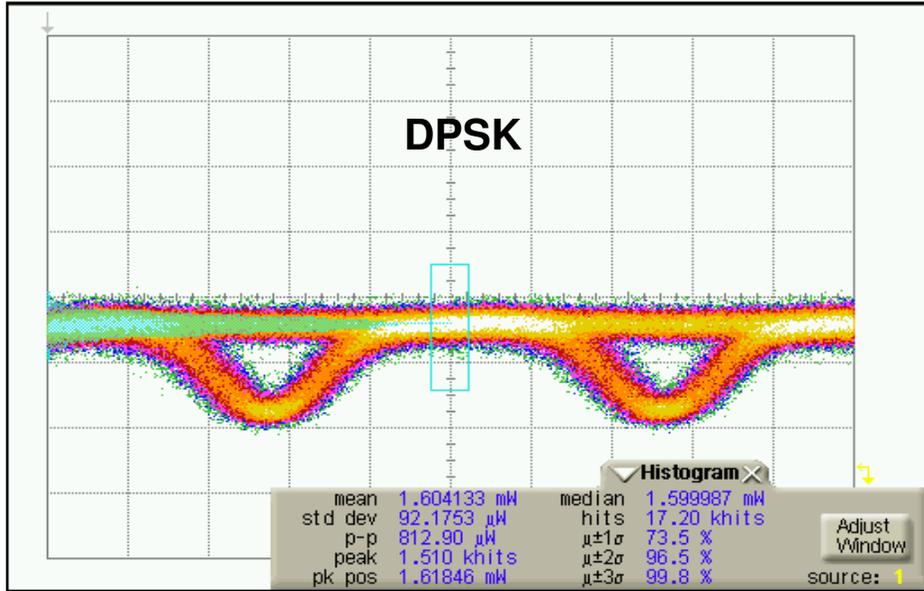
Measured Data

Bias Conditions: Vd = 7 V, Idq = 293 mA,
Vg1,2,3 = -0.5, -1.7, -0.9 V, Vc1,2,3 = 0.7, 0.7, 0.7 V Typical

Measured Data: Vin = 0.5 Vpp, 21.5 Gb/s, Vd = 7V

RMS Source Jitter = 673 fs
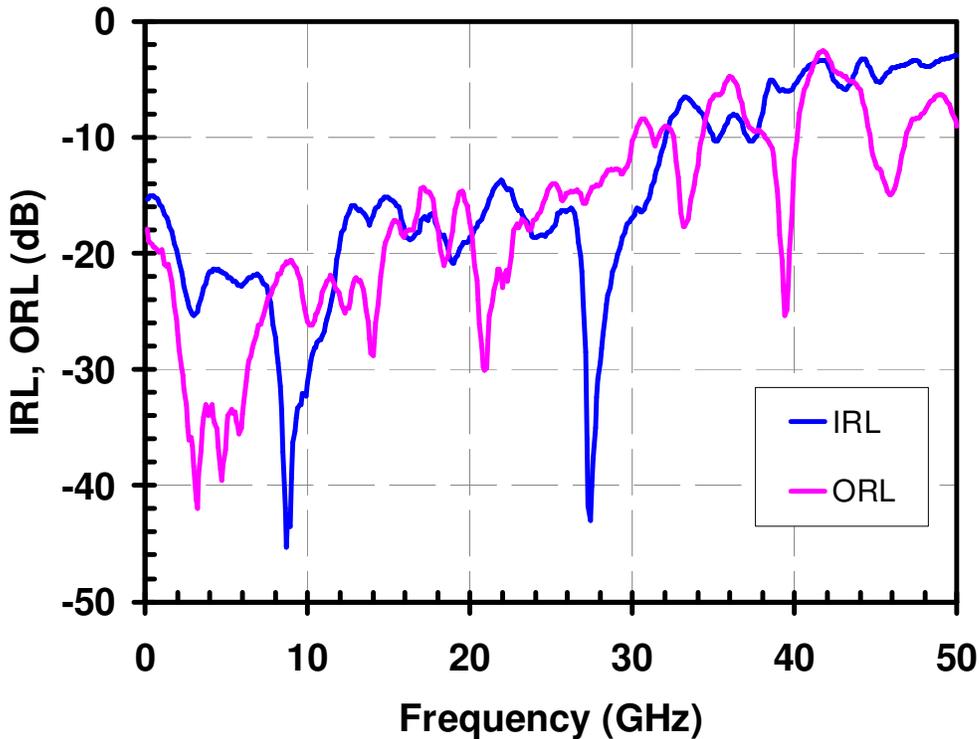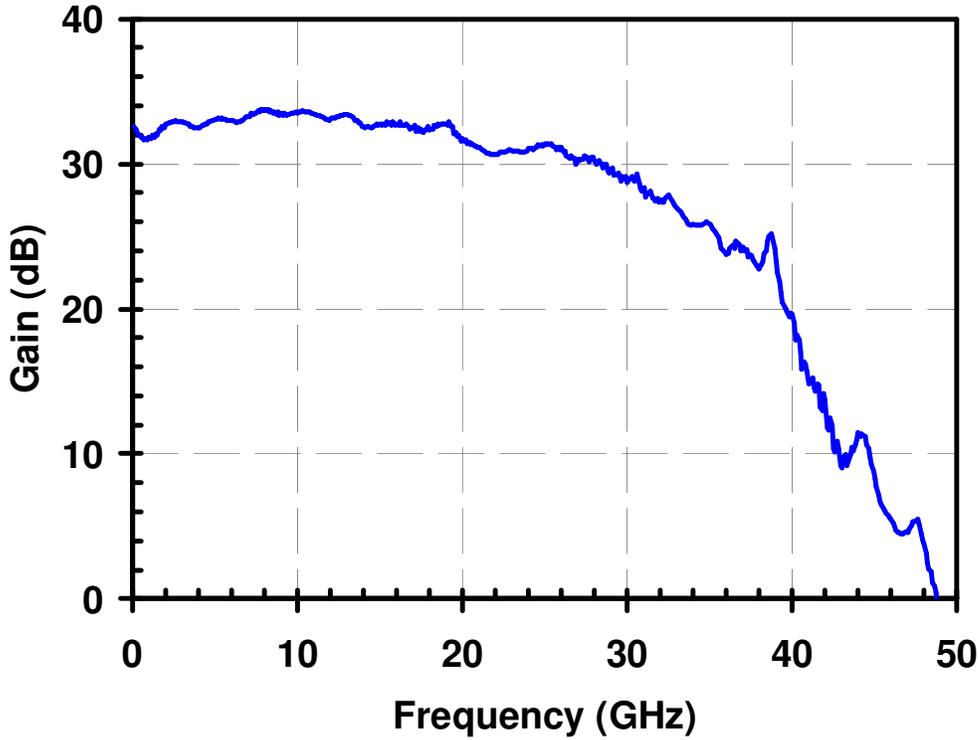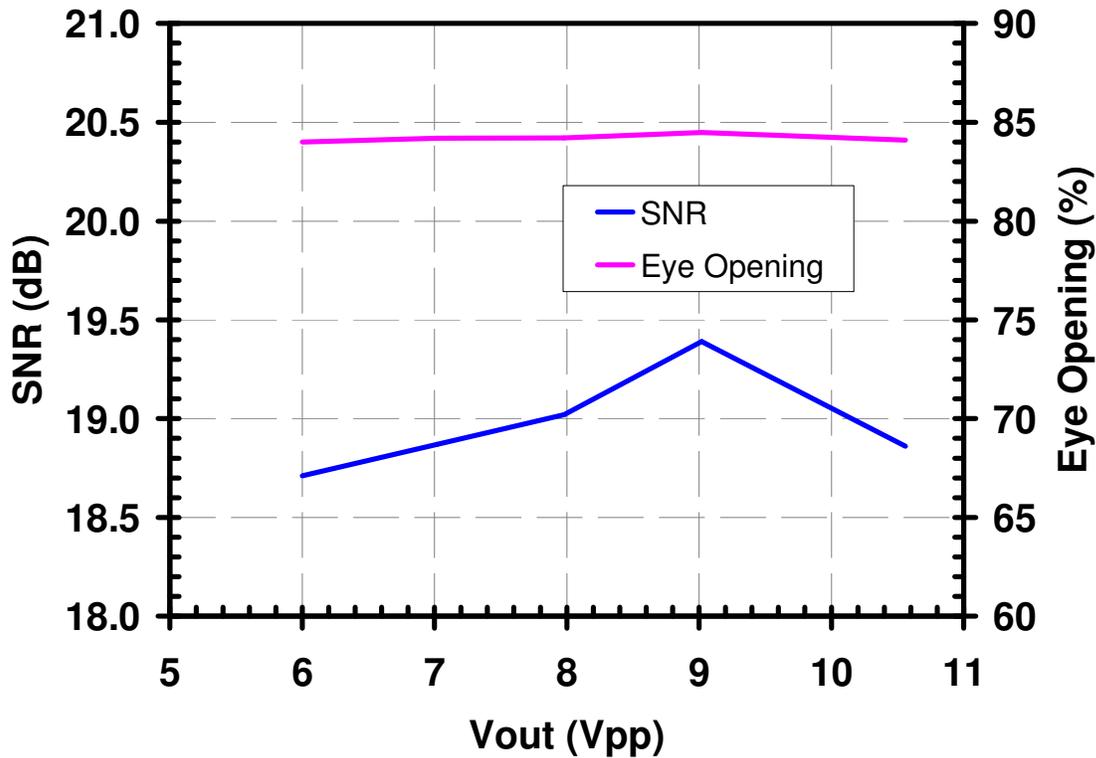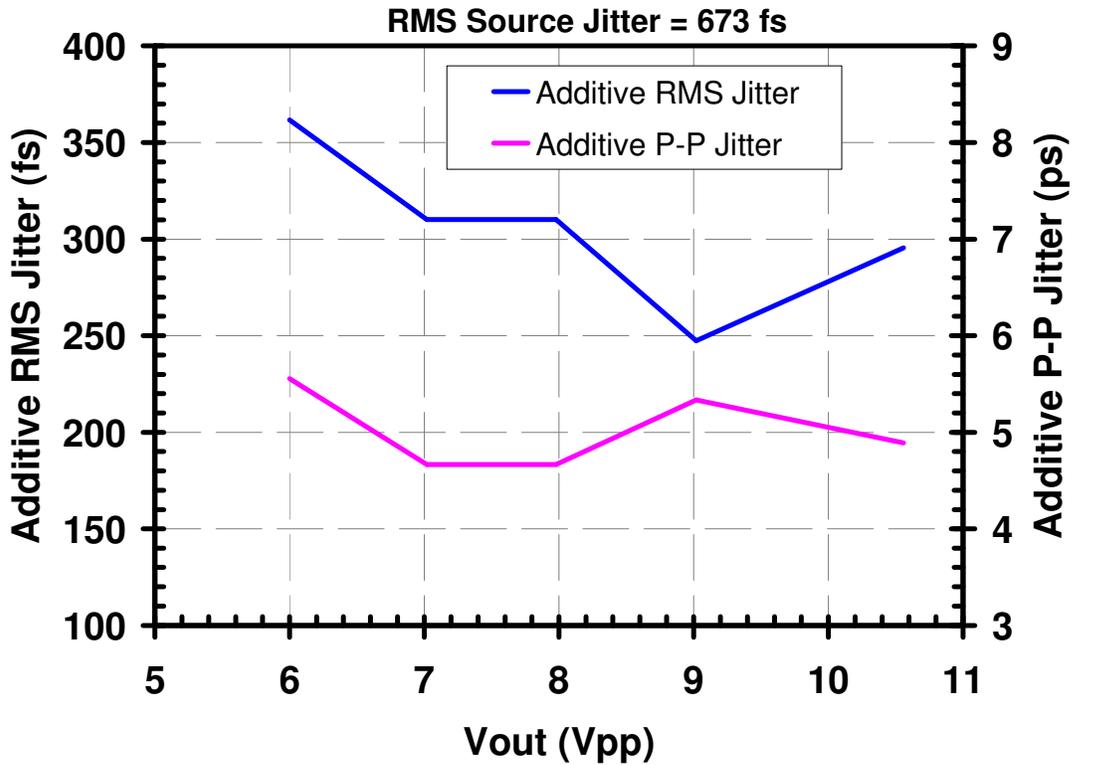
Measured Data: Vin = 0.5 Vpp, 21.5 Gb/s, Vd = 7 V
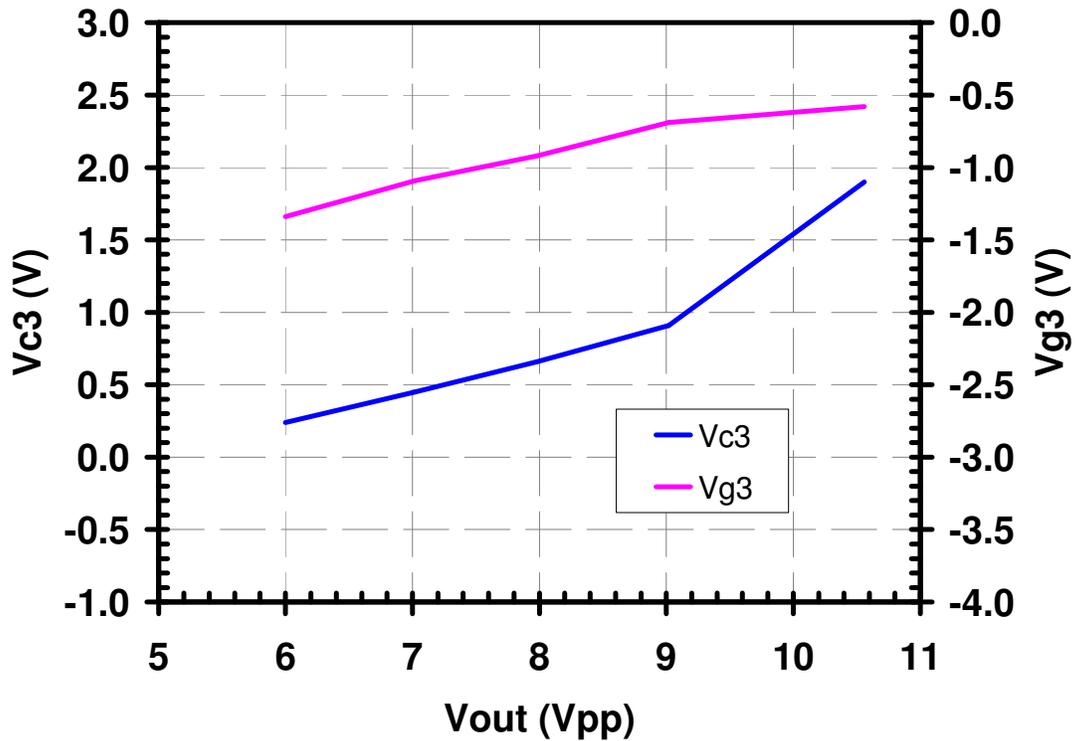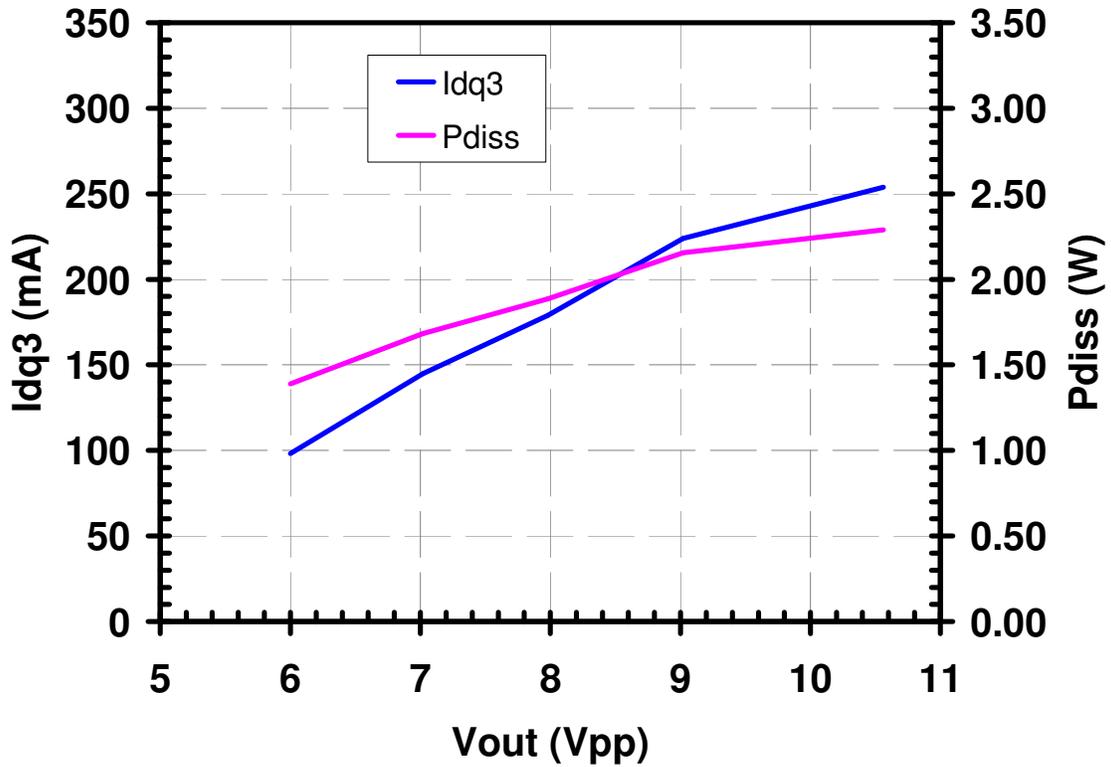
Measured Data: Vin = 0.5 Vpp, 21.5 Gb/s, Vd = 7 V
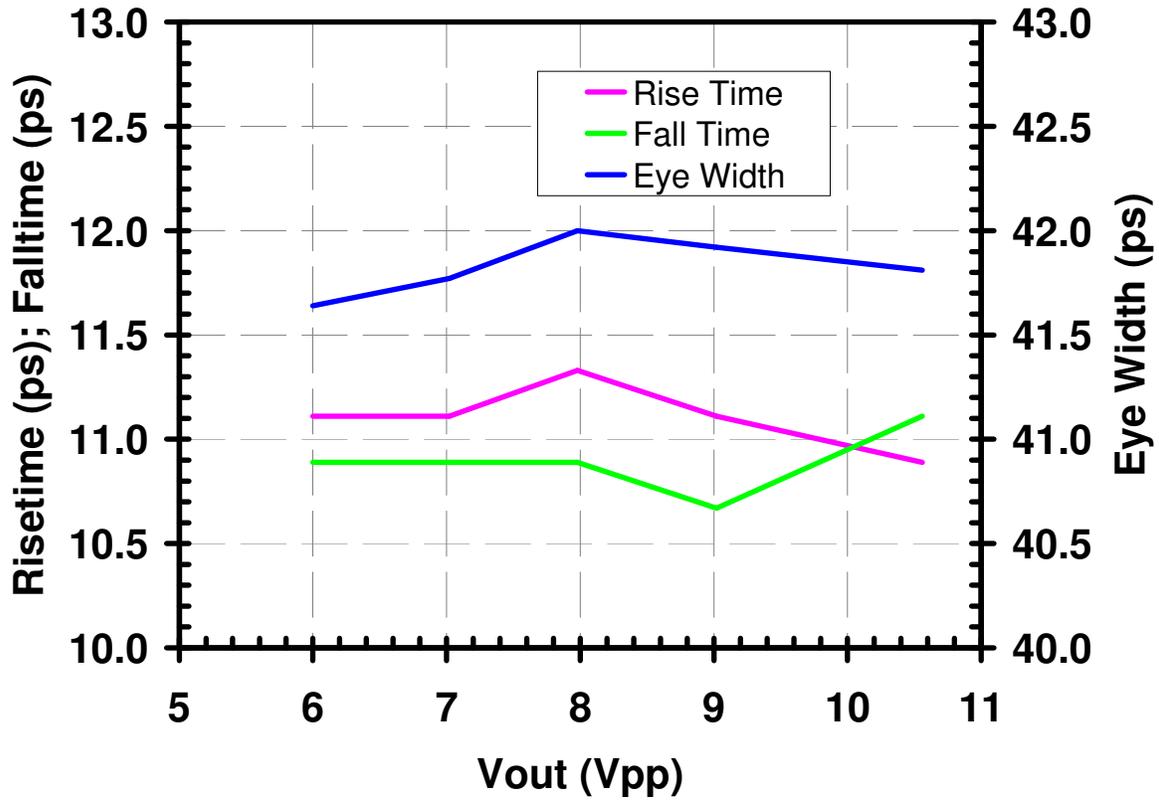
Ordering Information

Part	Package Style
TGA4943-SL	Land Grid Array, Surface Mount (RoHS)